

ABSTRACT

A porous-material-forming photo-curing resin composition comprising:

- 5 a photo-polymerizable monomer (A) having a surface tension of not more than 25×10^{-5} N/cm,
- an organic compound (B) that is non-compatible with the photo-polymerizable monomer (A),
- a common solvent (C) that is compatible with the photo-polymerizable monomer (A) and the organic compound (B); and
- a photo-polymerization initiator (D); and
- a porous resin cured product which is obtained by photo-curing the above composition and has a very low surface tension.

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